

ABSTRACT

Disclosed in the present invention is a wafer polishing system, comprising a wafer polishing unit, a wafer cleaning unit which is arranged adjacent to the wafer polishing unit, a wafer transport channel, and a wafer transfer mechanism, at least part thereof being located in the wafer cleaning unit. A docking station is formed on the wafer transport channel, and at least part of the wafer transfer mechanism can move to the docking station, so as to transport wafers between the wafer polishing unit and the wafer cleaning unit. Further disclosed in the present invention is a wafer processing method of the wafer polishing system. In the present invention, part of the wafer transfer mechanism is located in the wafer cleaning unit, and said part can move to the docking station so as to achieve direct interaction between the wafer polishing unit and the wafer cleaning unit without any intermediate interaction link. Moreover, shortening the transfer path of wafers also reduces devices needed for wafer transferring, thereby minimizing the damage to wafers and achieving high efficiency of wafer transferring.

FIG. 1